

2020 IEEE VTS

April 05-08, 2020
SAN DIEGO, USA



TEST RELIABILITY AND SECURITY CHALLENGES IN VLSI SYSTEMS

CALL FOR PAPERS

The IEEE VLSI Test Symposium (VTS) explores emerging trends and novel concepts in testing, reliability and security of microelectronic circuits and systems. The VTS Program Committee invites original, unpublished **paper submissions** for VTS 2020. Proposals for the **innovative practices** and **special sessions** tracks are also invited.

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Major topics include but are not limited to:

Analog/Mixed-Signal/RF Test	Embedded System & Board Test	Power/Thermal Issues in Test
ATPG & Compression	Embedded Test Methods	System-on-Chip (SOC) Test
Silicon Debug	Emerging Technologies Test	Test Standards & Economics
Automotive Test & Safety	FPGA Test	Test of Biomedical Devices
Built-In Self-Test (BIST)	Fault Modeling and Simulation	Test of High-Speed I/O
Defect & Current Based Test	Hardware Security	Test Quality and Reliability
Defect/Fault Tolerance	Low-Power IC Test	Test Resource Partitioning
Delay & Performance Test	Microsystems/MEMS/Sensors Test	Transients and Soft Errors
Design for Testability (DFT)	Memory Test and Repair	2.5D, 3D and SiP Test
Design Verification/Validation	On-Line Test & Error Correction	Yield Optimization

New hot topics:

VTS puts particular emphasis on enlarging its scope soliciting submissions on aspects on the following hot topics:
Testing AI and Neuromorphic Devices, Machine Learning for Test, Test/Reliability/Security in Approximate and Quantum Computing.

KEY DATES

Oct 4, 2019 - Title/Abstract Registration
Oct 11, 2019 - Paper (PDF) upload
Dec 10, 2019 - Notifications
Feb 7, 2020 - Camera ready upload

Submissions

6 pages in a standard IEEE
two columns format.

Submit at:
<http://www.tttc-vts.org>

VTS 2020 will present a Best Paper Award, a Best Special Session Award, and a Best Innovative Practices Session Award based on the evaluations of reviewers, attendees, and an invited panel of judges. We also plan to organize various Student Activities including the TTTC Best Doctoral Thesis Contest, details for which will be made available through the VTS website.

General Co-Chair



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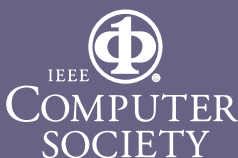


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Steering Committee:

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